

IN THE CLAIMS:

1. (Currently Amended) A manufacturing method of a display device, ~~characterized in that comprising:~~

forming a conductive film over a substrate by ejecting liquid droplets containing conductive particles ~~are ejected on a film being processed~~ by using a first liquid droplet ejecting apparatus having comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly to form a conductive film locally;

forming a resist pattern locally on the conductive film by using a second liquid droplet ejecting apparatus having comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly; and

forming a wiring by etching the conductive film ~~the conductive film is etched~~ with the resist pattern as a mask at an atmospheric pressure or a pressure close to the atmospheric pressure by using a plasma generating means comprising one pair of electrodes to form a wiring.

2. (Canceled).

3. (Currently Amended) A manufacturing method of a display device according ~~to the manufacturing methods of claim 1 [[or 2]], wherein after etching the conductive film~~ forming the wiring, the resist film is locally etched at an atmospheric pressure or a pressure close to the atmospheric pressure by using the plasma generating means provided with [[a]] one pair of cylindrical electrodes or the plasma generating means provided with a plurality of pairs of cylindrical electrodes arranged linearly.

4. (Currently Amended) A manufacturing method of a display device, characterized in that comprising:

after forming a conductive film [[on]] over a substrate being processed, an unnecessary portion of the conductive film is locally etched by using a plasma generating means provided with a pair of cylindrical electrodes or a plasma generating means provided with a plurality of pairs of cylindrical electrodes arranged linearly at an atmospheric pressure or a pressure close to the atmospheric pressure to form a wiring by ejecting liquid droplets containing conductive particles by using a liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly; and

after forming the conductive film, forming a wiring by etching an unnecessary portion of the conductive film locally by using a plasma generating means provided with one pair of electrodes at an atmospheric pressure or a pressure close to the atmospheric pressure.

5. (Currently amended) A manufacturing method of a display device, characterized in that comprising:

after forming a conductive film [[on]] over a substrate being processed by using a liquid droplet ejecting apparatus comprising a liquid droplet ejecting head provided with a plurality of liquid droplet ejecting nozzles arranged linearly an unnecessary portion of the conductive film is locally etched by using a plasma generating apparatus provided with a pair of cylindrical electrodes or plasma generating means provided with a plurality of pairs of cylindrical electrodes arranged linearly at an atmospheric pressure close to the atmospheric pressure to form a wiring; and

forming a resist pattern on the conductive film;

after forming the resist pattern, forming a wiring by etching an unnecessary portion of the conductive film locally by using a plasma generating means provided with one pair of electrodes at an atmospheric pressure or a pressure close to the atmospheric pressure.

6. (New) A manufacturing method of a display device according to claim 1, wherein the wiring includes at least one conductive material selected from the group consisting of Ag,

Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

7. (New) A manufacturing method of a display device according to claim 4, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

8. (New) A manufacturing method of a display device according to claim 5, wherein the wiring includes at least one conductive material selected from the group consisting of Ag, Au, Cu, Ni, Pt, Pd, Ir, Rh, W, and Al, metal sulfide of Cd and Zn, oxide of Fe, Ti, Si, Ge, Si, Zr, Ba, and the like, and fine particles or dispersible nanoparticles of silver halide.

9. (New) A manufacturing method of a display device according to claim 5, wherein after forming the wiring, the resist film is etched at an atmospheric pressure or a pressure close to the atmospheric pressure by using the plasma generating means provided with one pair of electrodes.

10. (New) A manufacturing method of a display device according to claim 1, wherein the one pair of electrodes are cylindrical electrodes.

11. (New) A manufacturing method of a display device according to claim 4, wherein the one pair of electrodes are cylindrical electrodes.

12. (New) A manufacturing method of a display device according to claim 5, wherein the one pair of electrodes are cylindrical electrodes.